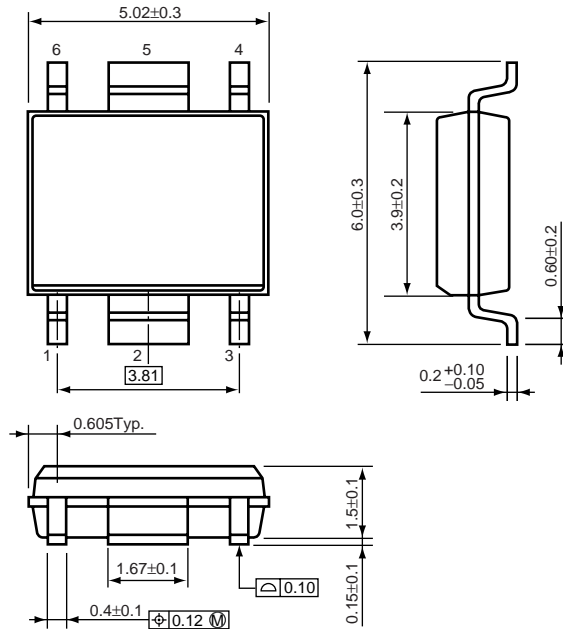


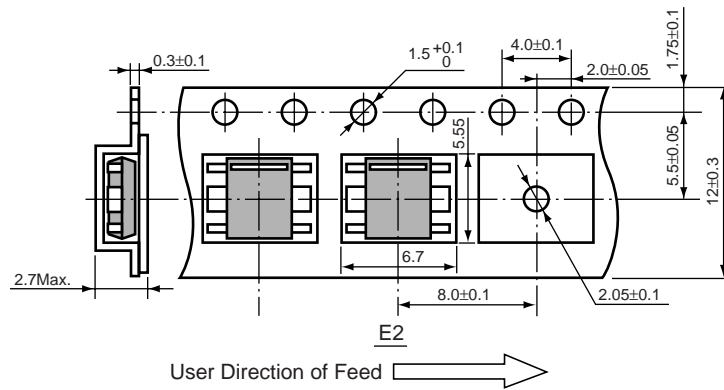
• HSOP-6J

Unit: mm

PACKAGE DIMENSIONS

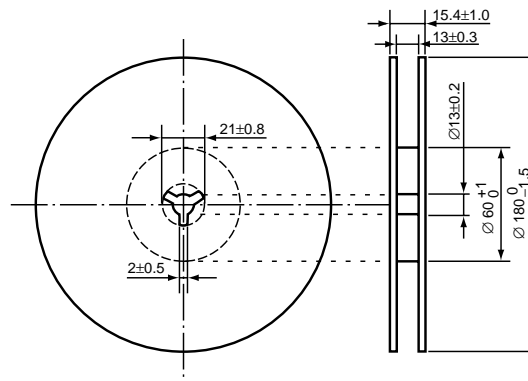


TAPING SPECIFICATION



TAPING REEL DIMENSIONS REUSE REEL (EIAJ-RRM-12Bc)

(1reel=1,000pcs)



POWER DISSIPATION (HSOP-6J)

This specification is at mounted on board. Power Dissipation (P_b) depends on conditions of mounting on board. This specification is based on the measurement at the condition below:

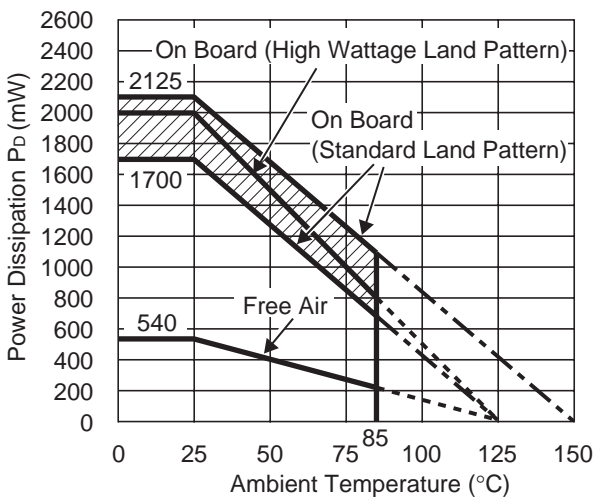
Measurement Conditions

	High Wattage Land Pattern	Standard Land Pattern
Environment	Mounting on Board (Wind velocity=0m/s)	Mounting on Board (Wind velocity=0m/s)
Board Material	Glass cloth epoxy plastic (Double sided)	Glass cloth epoxy plastic (Double sided)
Board Dimensions	50mm × 50mm × 1.6mm	50mm × 50mm × 1.6mm
Copper Ratio	90%	50%
Through-holes	φ0.5mm × 24pcs	φ0.5mm × 24pcs

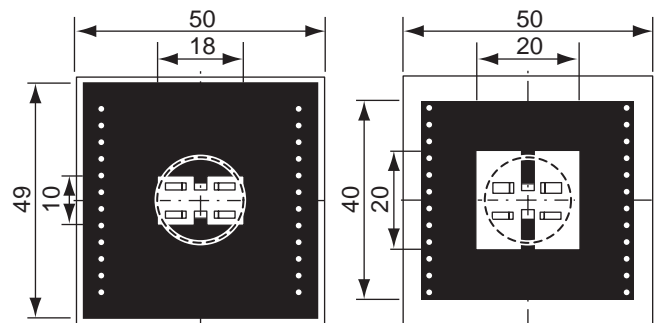
Measurement Results

($T_{opt}=25^{\circ}C, T_{jmax}=125^{\circ}C$)

	High Wattage Land Pattern	Standard Land Pattern	Free Air
Power Dissipation	2000mW	1700mW	540mW
Thermal Resistance	50°C/W	59°C/W	185°C/W
			$\theta_{jc}=17.5^{\circ}C/W$



Power Dissipation



High Wattage Standard

Measurement Board Pattern

○ IC Mount Area (Unit: mm)

The above graph shows the Power Dissipation of the package based on $T_{jmax}=125^{\circ}C$ and $T_{jmax}=150^{\circ}C$.

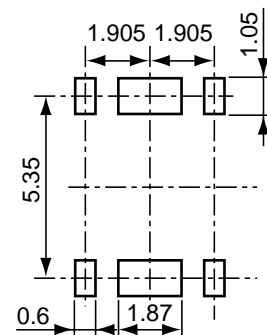
Operating the IC in the shaded area in the graph might have an influence it's lifetime.

Operating time must be within the time limit described in the table below, in case of operating in the shaded area.

Product Name	Operating time	Estimated years
RP131S	1,500 hrs	1 year

*The volume is calculated on the supposition that operating four hours/day.

RECOMMENDED LAND PATTERN



(Unit: mm)